*Topic:*

( ) wafer-level packaging ( ) substrate bonding ( ) testing and reliability ( ) non-semiconductor ( ) wafer bonding equipment, market, trends

*Bonding Technology*

( ) glass ( ) direct ( ) hybride ( ) SAB ( ) adhesive ( ) metal ( ) others

*Abstract (text + picture):*

*Affiliations:*

**WaferBond’25**

**- Abstract Submission Form -**

*Title:*

*Authors:*